# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**  
[List multiple models if applicable.]

HP EliteOne 800 G3 Non-Touch GPU All-in-One Business PC

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm MB<em>1, Memory</em>2, SSD*1</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries RTC</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LED</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

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Components, parts and materials containing radioactive substances

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Star(Torx) screwdriver OD 3.3mm..</td>
<td></td>
</tr>
<tr>
<td>Cross(Philips) screwdriver OD 3.0mm</td>
<td></td>
</tr>
<tr>
<td>Cross(Philips) screwdriver OD 2.0mm</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Refer to 1~4 to disassemble rear cover and IO pocket
2. Refer to 5~6 to disassemble VESA bracket and Fan
3. Refer to 7~8 to disassemble Thermal module
4. Refer to 9~12 to disassemble HDD and ODD
5. Refer to 13~14 to disassemble Webcam module
6. Refer to 15~16 to disassemble WLAN card and SSD card
7. Refer to 17~18 to disassemble Power supply and Audio jack cable
8. Refer to 19 to disassemble IO shielding
9. Refer to 20~22 to disassemble Power button board and Finger print
10. Refer to 23~25 to disassemble MB and CPU and Memory
11. Refer to 26~27 to disassemble Thermal pad and Base pan
12. Refer to 28 to disassemble Speaker and Antenna
13. Refer to 29 to disassemble LVDS and Backlight cable and Touch cable
14. Refer to 30 to disassemble LCD
15.
16.
17.
18.
19.
20.
21.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

AIO system disassembly
1. Place the system
2. Remove the stand, push the button on red circle location

3. Remove rear cove, pull up the rear cover on red circle location then remove rear cover
4. Remove IO pocket, release 2 screws on red circle location remove IO pocket

   Tool: Star(Torx) screwdriver OD 3.3mm

5. Remove VESA bracket with Fan, release 5 screws on red circle location to remove VESA bracket with Fan

   Tool: Star(Torx) screwdriver OD 3.3mm
6. Remove Fan from VESA bracket, release 4 screws on red circle location to remove Fan from VESA bracket

   Tool: Star(Torx) screwdriver OD 3.3mm

7. Remove thermal module (UMA SKU), release 6 screws on red circle location to remove thermal module

   Tool: Star(Torx) screwdriver OD 3.3mm
8. Remove HDD with HDD cage, release 1 screw on red circle location and remove the DC power cable from the hook on red circle location to remove HDD with HDD cage

Tool: Star(Torx) screwdriver OD 3.3mm
9. Remove HDD from cage, slide HDD out from the cage then release 4 gromet to remove HDD from cage.

   Tool: Cross(Philips) screwdriver OD 3.0mm

10. Remove ODD, push the ODD latch on red circle location to slide out the ODD.
11. Remove ODD latch and bezel
12. Remove Webcam module box, release 3 screws on red circle to remove Fan dust then release 4 screws on yellow screws and unplug webcam connector on yellow circle location from MB

Tool: Star(Torx) screwdriver OD 3.3mm
Cross(Phillips) screwdriver OD 3.0mm

13. Remove Webcam and Dmic, release 3 screws to remove Webcam box cover then remove Webcam and Dmic
Tool: Cross (Philips) screwdriver OD 2.0mm
14. Remove WLAN card, release 1 screws on red circle on location and unplug the antenna on yellow circle location to remove WLAN card

   Tool: Cross(Philips) screwdriver OD 2.0mm

15. Remove SSD card, release 1 screw on red circle location to remove SSD card

   Tool: Cross(Philips) screwdriver OD 2.0mm
16. Remove Power supply, release 3 screws on red circle location then unplug connector on yellow circle location to remove Power supply

Tool: Star(Torx) screwdriver OD 3.3mm
17. Remove Audio jack cable, release 1 screw on red circle location and unplug connector from MB on yellow circle location to remove Audio jack cable

   Tool: Star(Torx) screwdriver OD 3.3mm
18. Remove IO shielding, release 5 screws to remove IO shielding

Tool: Star(Torx) screwdriver OD 3.3mm
19. Remove Power button board with bracket, release 1 screw on red circle location and unplug connector on yellow circle location from MB

Tool: Star(Torx) screwdriver OD 3.3mm
20. Remove Power button board from bracket, release 2 screws on red circle location to remove Power button board from bracket.

Tool: Cross (Philips) screwdriver OD 2.0mm
21. Remove Finger print module (Touch SKU), release 2 screws on red circle location to remove Finger print module

   Tool: Cross(Philips) screwdriver OD 2.0mm

22. Remove MB, remove LVDS on red circle location from MB then release 9 screws on yellow circle location to remove MB

   Tool: Star(Torx) screwdriver OD 3.3mm
23. Remove CPU, push down the latch on red circle location to remove CPU
24. Remove Memory, push latch on red circle location to remove Memory

25. Remove Thermal pad, remove Thermal pad on red circle location
26. Remove Base pan, release 12 screws on red circle location to remove Base pan from Middle frame

Tool: Cross (Philips) screwdriver OD 3.0mm
27. Remove Speaker, release 4 screws on red circle location to remove Speaker

Tool: Star(Torx) screwdriver OD 3.3mm
28. Remove L+R Antenna, tear the Antenna(L+R) on red circle location to remove Antenna(L+R)
29. Remove LVDS, Backlight cable, Touch cable (Touch SKU), remove LVDS, Backlight cable, Touch cable on red circle location to remove cables from LCD.
30. Remove LCD from Middle frame, rotate the Middle Frame as the picture to remove LCD from Middle Frame.
PSG instructions for this template are available at EL-MF877-01